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Attorney Docket No. 1057

PATENT

22390 U.S. PTO  
10/731436



Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

The patent application of

Inventor(s): TAKEO KURAMOTO ET AL

For: SOLDER BALL ASSEMBLY FOR BUMP FORMATION AND  
METHOD FOR ITS MANUFACTURE

is attached for filing.

[X] This application is being filed without a declaration or fee.

[X] This application claims the priority of Japanese Patent Application No. 2002-359405 filed on December 11, 2002.

Respectfully submitted,

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